

FIG. 1

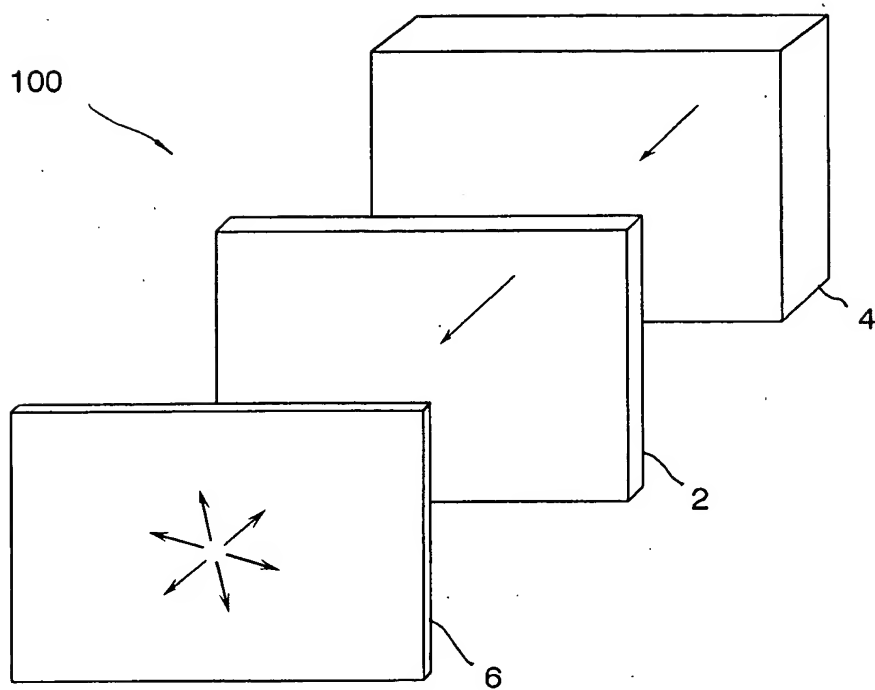


FIG. 2

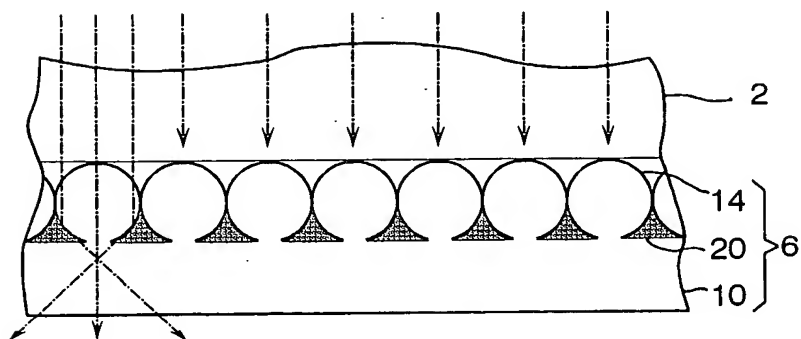


FIG. 3

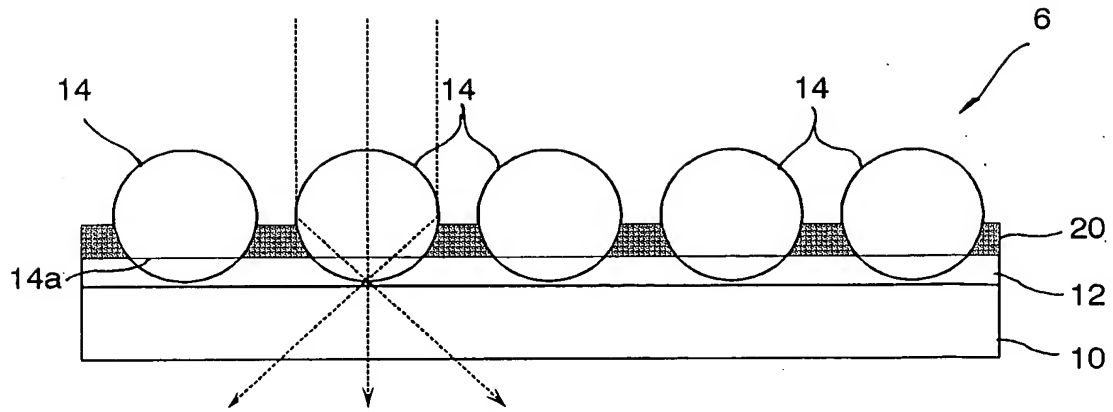
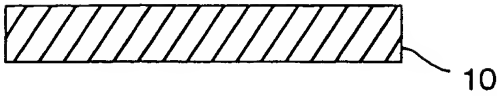
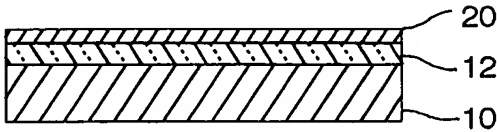


FIG. 4

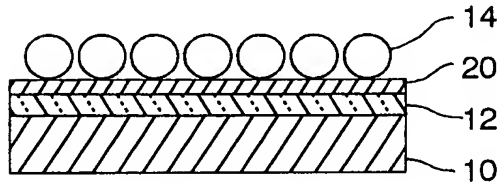
STEP I



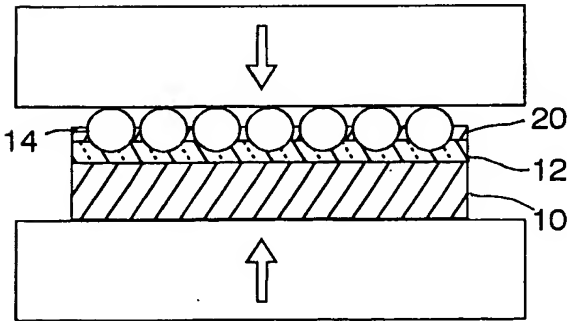
STEP II



STEP III



STEP IV



STEP V

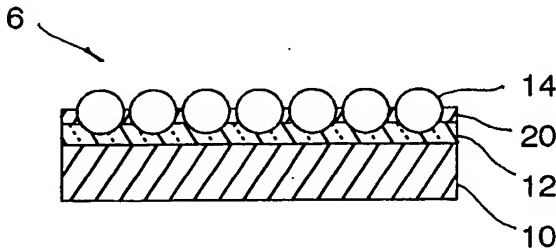


FIG. 5

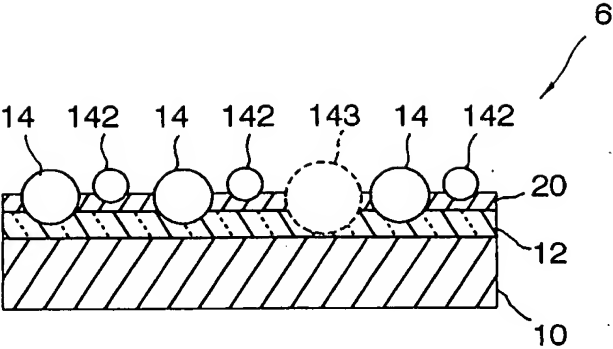


FIG. 5 is a cross-sectional view of a device structure 6. The device structure 6 includes a substrate 10, a layer 12, and a layer 20. The layer 20 includes a plurality of circular features 14, 142, and 143. The features 14, 142, and 14 are solid circles, and the feature 143 is a dashed circle.

FIG. 6

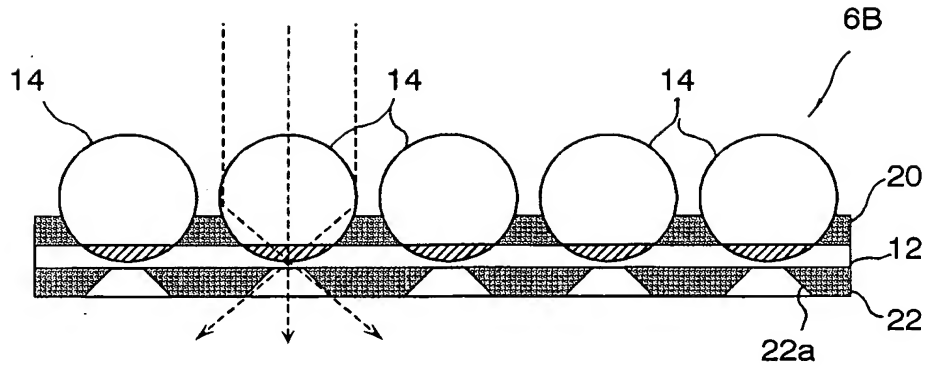


FIG. 7

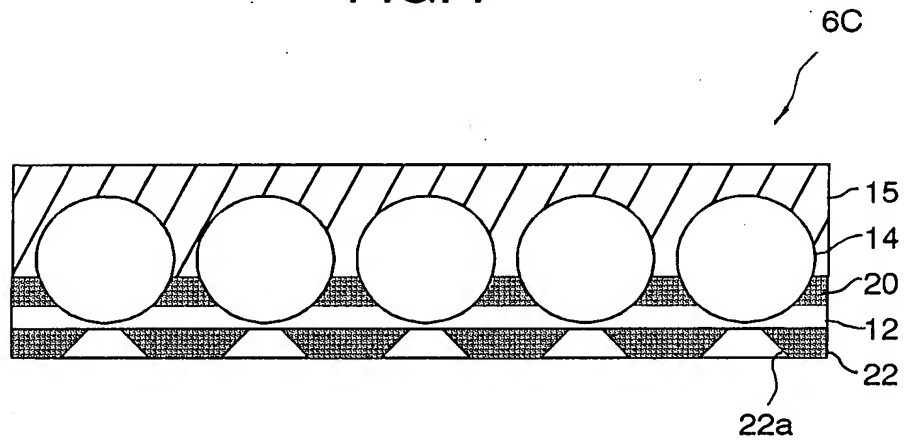


FIG. 8

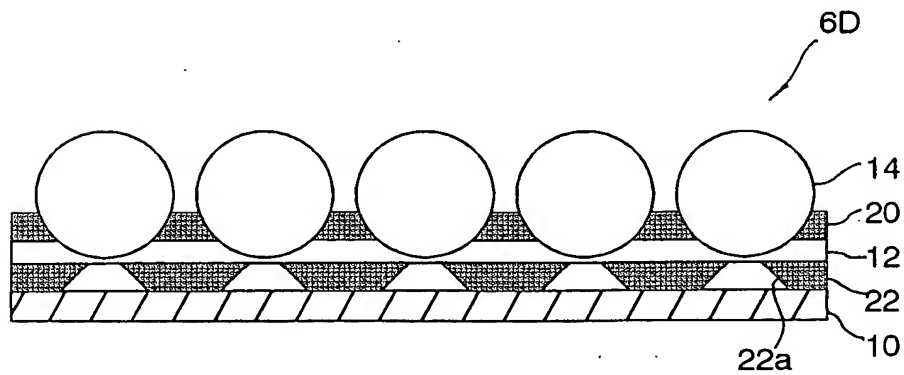
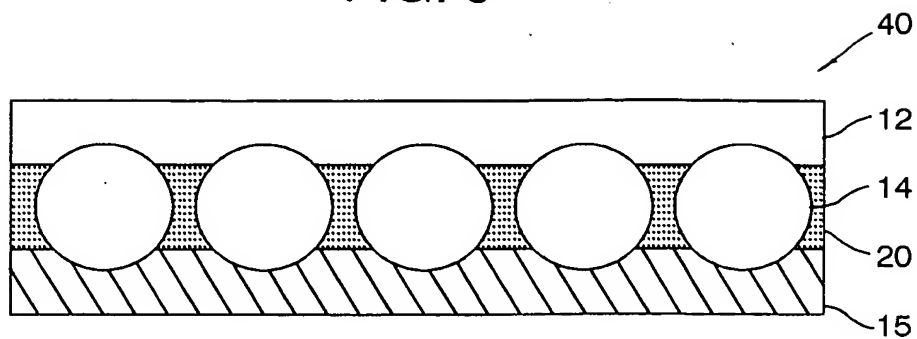
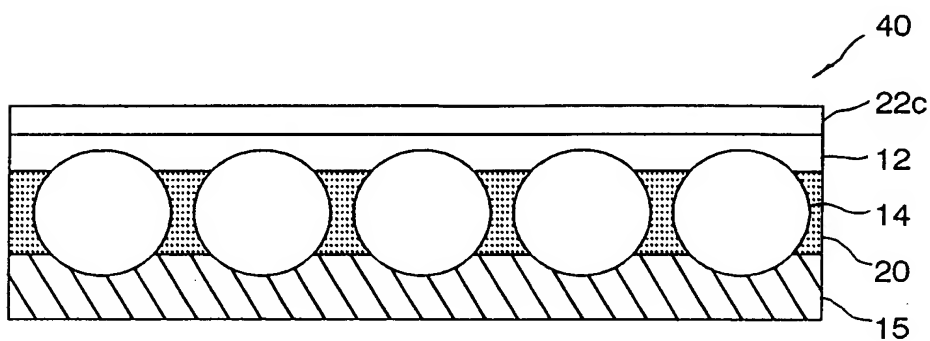


FIG. 9

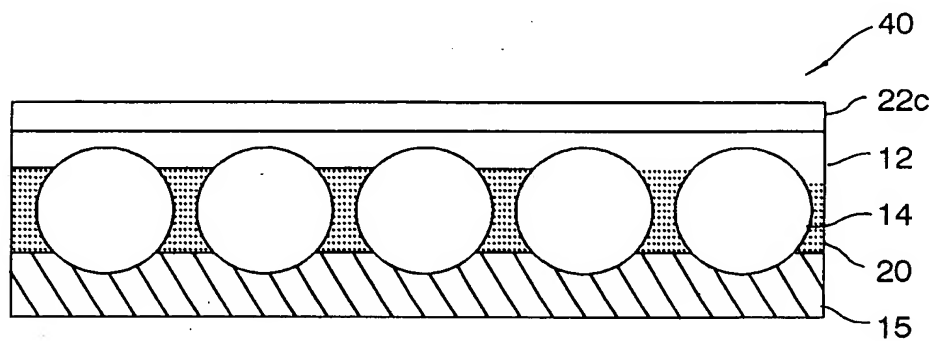
STEP I



STEP II



STEP III



STEP IV

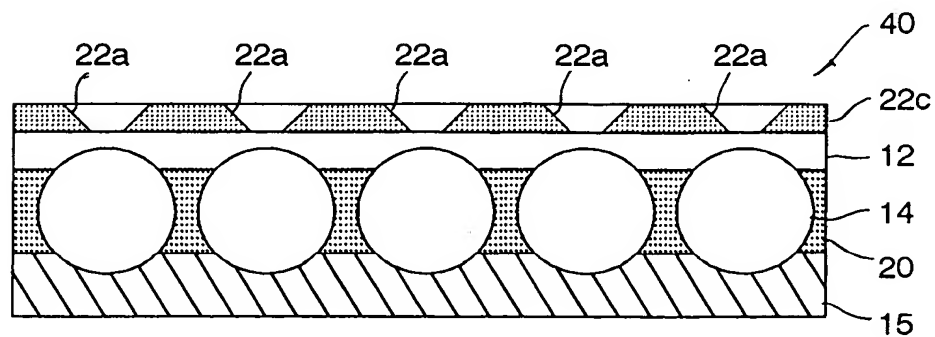


FIG. 10

